



Product Change Notification

Change Notification #: 115655 - 00
Change Title: Intel® Server System R2208WTTYC1R and Intel® 2U Hot-swap Drive Cage Upgrade Kit with 4x NVMe SSD Support A2U44X25NVMEDK, PCN 115655-00, Product Design, Risers signal and electrical improvements
Date of Publication: July 06, 2017

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	July 22, 2017
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** Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.*

Description of Change to the Customer:

Intel Corporation is implementing changes to the Intel® Server System R2208WTTYC1R and the Intel® 2U Hot-swap Drive Cage Upgrade Kit with 4x NVMe SSD Support A2U44X25NVMEDK products listed in the “Products Affected/Intel Ordering Codes” table. These changes have been made in order to support Power Reduction/Throttle function when Graphic Processing Unit (GPU) cards are installed or supported Intel® Xeon Phi cards. Please see the changes that have been implemented:

1. The reset pin in the MUX will be connected to the BMC (using RST_MIC_MUX_N from 230PIN RISER; Pin B10) in the same manner that it's done for MUX located on the baseboards. Risers affected:
 - 1U 1Slot PCIe RISER
 - 2U 2Slot PCIe RISER
 - 2U 3Slot PCIe RISER
2. Signal changes: signal FM_PHI_THROTTLE_N (OD signal from Baseboard) from pin A9 of the edge connector and also an individual N-FET on pin B12 will be added and pin B30 of each PCIe slot of 2U 2Slot Risers.

Note: This change does not apply on the 1U, 1 Slot Riser or the 2U 2 Slot 3rd Riser.

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications.

Products Affected / Intel Ordering Codes:

	Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
Intel® Server System R2208WTTYC1R	R2208WTTYC1R	943828	J11487-008	N/A	J11487-009	N/A
Intel® 2U Hot-swap Drive Cage Upgrade Kit with 4x NVMe SSD Support	A2U44X25NVMEDK	936253	H47011-002	H20083-005	H47011-003	H20083-007

PCN Revision History:

Date of Revision:

July 06, 2017

Revision Number:

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Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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